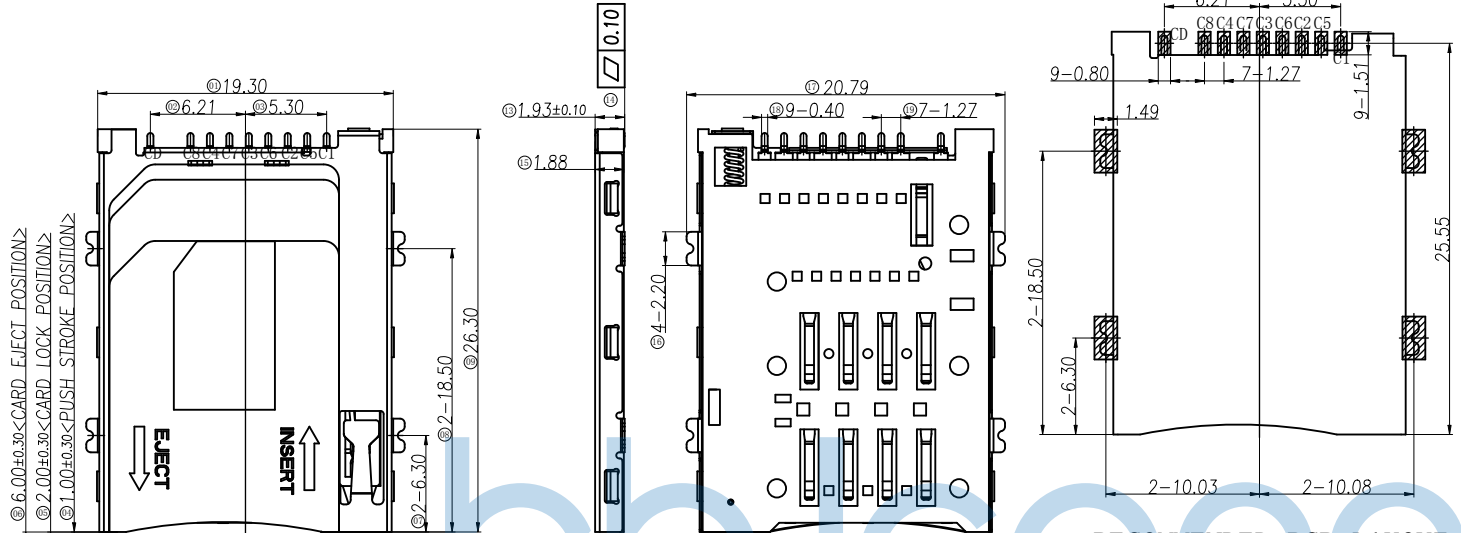


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTES:

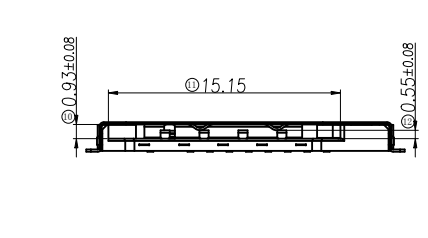
- MATERIAL:**
HOUSING: High Temperature Thermoplastic LCP E130i
Terminal: Copper Alloy C5191
Shell: Stainless Steel SUS304
- PLATING:**
Terminal: 50u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND TIN PLATED SOLDER AREA
Shell: 30u" Ni UNDERPLATED OVERALL
G/F PLATED ON SOLDER AREA
- TECHNICAL SPECIALITY:**
RATED VOLTAGE: 30VACMAX.
CURRENT RATING: 0.5AMAX.
INSULATION RESISTANCE: 1000MΩ MIN
CONTACT RESISTANCE: 50mΩ MAX
WITHSTANDING VOLTAGE: 500VACFOR1MINUTES
OPERATING TEMPERATURE: -40℃ ~ +85℃ Humidity 80%R. HMAX



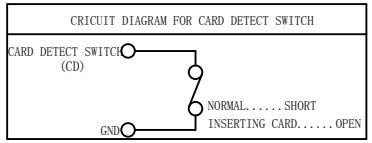
RECOMMENDED PCB LAYOUT

TOLERANCE: ±0.05

- SMT SOLDER AREA
 - COPPER RESTRICTED AREA
1. TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
 2. NO FIRST PCB LAYOUT CIRCUITS IN THE AREA



Card specifications



PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED
CD	Detect Switch



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PDWG.NO: 0302-1

深圳市步步精科技有限公司

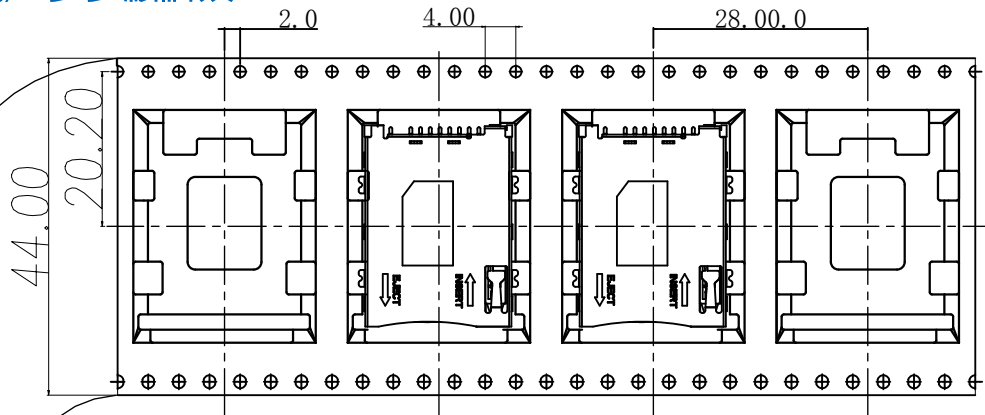
NAME: 卡座 SIM Card Push-Push 8P 带CDPIN H=1.93 贴片 无柱

APPD. JM_Zheng
 CHKD. LYX
 DR. TSP

PJ. NO.: CD.02.02-13-0009
 SIZE: A4 DRW NO.:
 FINISH: SEE NOTES MAT'L.: SEE NOTES
 SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2

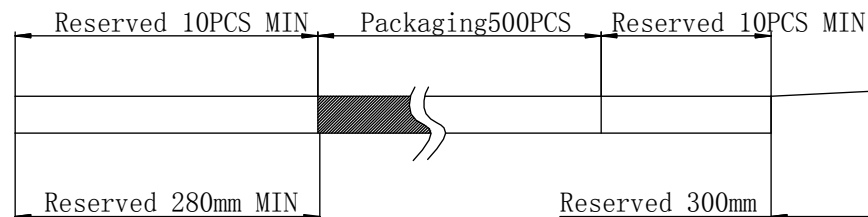
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

Direction of use →

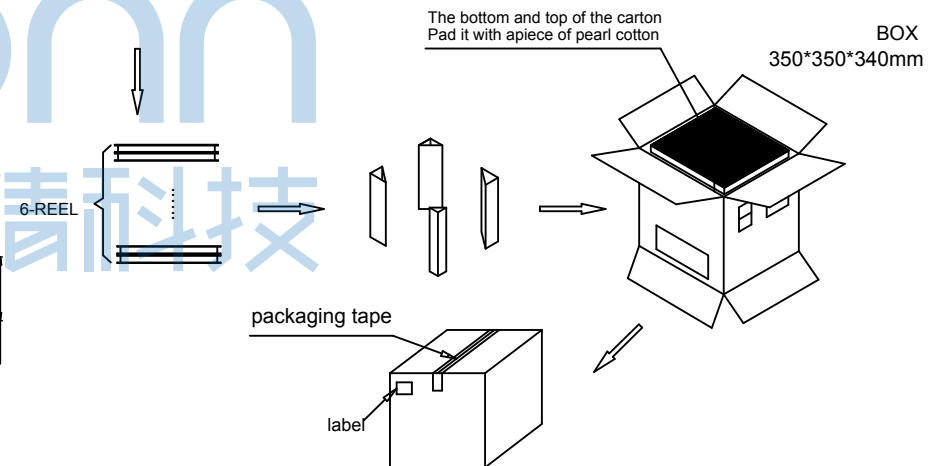
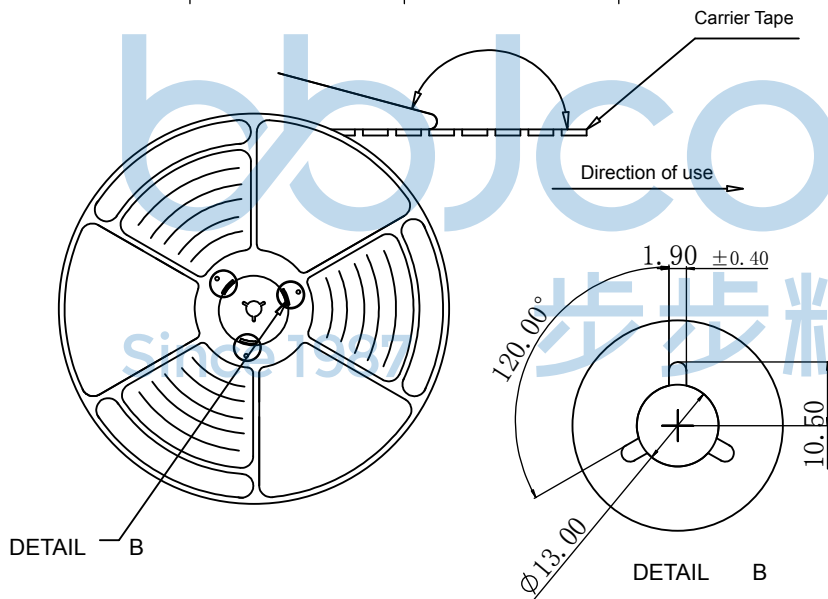


NOTES:

- 1、Packing quantity per plate: 500PCS/Plate
- 2、Loading and packing method



- 3、Total packaging: 3000PCS/Box



Description	Quantity
Carrierband (Lucent, PET W=44 PH=28,T=0.3)	87.36m
Box (K=K,T=7.0,350*350*340)	1PCS
PE Bag (T=0.08mm, 730*760*730)	1PCS
Self-adhesive (W=37.50)	89.16m
Beam (K=K, T=7.0,95*95*290)	4PCS
PearlWool (340*340*18)	2PCS
REEL (BLUE, 13Inches*44mm, φ330)	6PCS
1.93H PUSH-PUSH SIM CARD <SM016-100>	3000PCS



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X': ±3" .X': ±2" .XX': ±1"
APPD. JM_Zheng CHKD. LYX DR. TSP	NAME: 卡座 SIM Card Push-Push 8P 带CDPIN H=1.93 贴片 无柱 PJ. NO.: CD.02.02-13-0009 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2